COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: QCI

<table>
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<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: PMP21065A</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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<td>PLOT NAME = Top Assembly Drawing</td>
<td>GENERATED : 7/20/2017 3:30:30 PM</td>
<td>TEXAS INSTRUMENTS</td>
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